



NOTES:

1. MATERIAL: BLACK 94% Al₂O₃
2. METALLIZATION: MINIMUM 60μ INCHES GOLD OVER 50 TO 350μ INCHES NICKEL AND REFRACTORY METAL.
3. PARTS SUPPLIED TO GE CERAMICS STANDARD CHIP CARRIER SPECIFICATION.
4. DIE PAD CONNECTED TO INDEX CORNER.
5. DIE PAD, SEAL RING AND BONDING PADS ARE ELECTRICALLY ISOLATED.

REVISIONS					
C	REDRAWN TO ASIZE 7-15-86	RJB	EGD	BTH	
ISSUE	ISSUE DATE AND CHANGE RECORD	DR.	CH.	APP.	



GENERAL ELECTRIC CERAMICS, Inc.
 P.O. Box 4327
 CHATTANOOGA, TN 37405-0327

ALL DIMENSIONS IN INCHES
 TOLERANCES
 Unless Otherwise Specified
 +/- 1%
 Not Less Than +/- .005

TITLE: 16 LEAD CHIP CARRIER
 PART No: SU-88216-WC
 DWG No: 78-8044-2865-0